

1 Characteristics

Table 1. In compliance with the following standards

Standard	Peak surge voltage (V)	Waveform voltage	Required peak current (A)	Current waveform	Minimum serial resistor to meet standard (Ω)
GR-1089 Core First level	2500 1000	2/10 μ s 10/1000 μ s	500 100	2/10 μ s 10/1000 μ s	5 2.5
GR-1089 Core Second level	5000	2/10 μ s	500	2/10 μ s	10
GR-1089 Core Intra-building	1500	2/10 μ s	100	2/10 μ s	0
ITU-T-K20/K21	6000 1500	10/700 μ s	150 37.5	5/310 μ s	10 0
ITU-T-K20 (IEC61000-4-2)	8000 15000	1/60 ns	ESD contact discharge ESD air discharge		0 0
IEC61000-4-5	4000 4000	10/700 μ s 1.2/50 μ s	100 100	5/310 μ s 8/20 μ s	0 0
TIA/EIA IS-968, lightning surge type A	1500 800	10/160 μ s 10/560 μ s	200 100	10/160 μ s 10/560 μ s	2.5 0
TIA/EIA IS-968, lightning surge type B	1000	9/720 μ s	25	5/320 μ s	0

Table 2. Absolute ratings ($T_{amb} = 25\text{ }^{\circ}\text{C}$)

Symbol	Parameter	Conditions	Value	Unit
I_{PP}	Repetitive peak pulse current (see Figure 2)	10/1000 μs 8/20 μs 10/560 μs 5/310 μs 10/160 μs 1/20 μs 2/10 μs	80 200 100 120 150 200 250	A
I_{FS}	Fail-safe mode: maximum current ⁽¹⁾	8/20 μs	5	kA
I_{TSM}	Non repetitive surge peak on-state current (sinusoidal)	$t = 0.2\text{ s}$ $t = 1\text{ s}$ $t = 2\text{ s}$ $t = 15\text{ mn}$	14 8 6.5 2	A
I^2t	I^2t value for fusing	$t = 16.6\text{ ms}$ $t = 20\text{ ms}$	7.5 7.8	A^2s
T_{stg}	Storage temperature range		-55 to 150	$^{\circ}\text{C}$
T_j	Operating junction temperature range		-40 to 150	
T_L	Maximum lead temperature for soldering during 10 s.		260	

1. In fail safe mode the device acts as a short circuit.

Table 3. Thermal resistances

Symbol	Parameter	Value	Unit
$R_{th(j-a)}$	Junction to ambient (with recommended footprint)	100	$^{\circ}\text{C}/\text{W}$
$R_{th(j-l)}$	Junction to leads	20	$^{\circ}\text{C}/\text{W}$

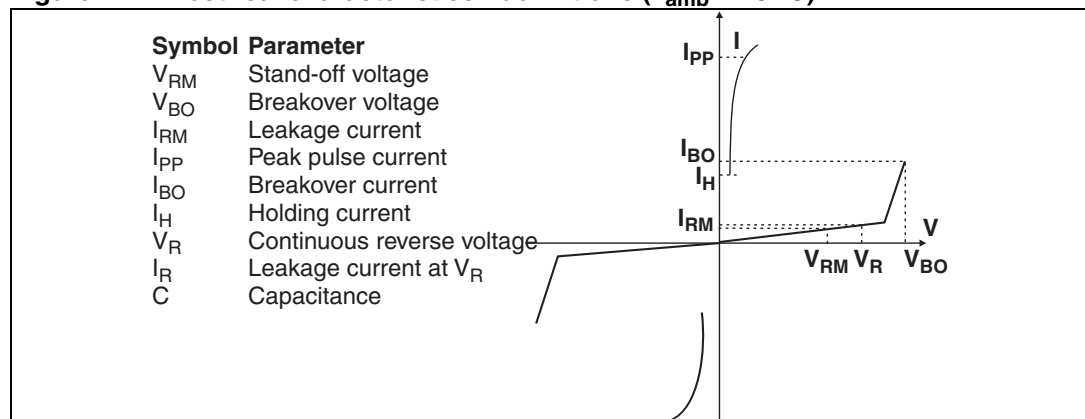
Figure 1. Electrical characteristics - definitions ($T_{amb} = 25\text{ }^{\circ}\text{C}$)

Table 4. Electrical characteristics - values ($T_{amb} = 25\text{ }^{\circ}\text{C}$)

Types	$I_{RM} @ V_{RM}$		$I_R @ V_R$		Dynamic $V_{BO}^{(1)}$	Static $V_{BO} @ I_{BO}^{(2)}$		$I_H^{(3)}$	$C^{(4)}$	$C^{(5)}$
	max.		max.		max.	max.	max.	min.	typ.	typ.
	μA	V	μA	V	V	V	mA	mA	pF	pF
SMP80MC-120	2	108	5	120	155	155	800	150	12	25
SMP80MC-140		126		140	180	180				
SMP80MC-160		144		160	205	205				
SMP80MC-200		180		200	255	255				
SMP80MC-230		207		230	295	295				
SMP80MC-270		243		270	345	345				
SMP80MC-320		290		320	400	400				

1. See [Figure 10: Test circuit 1 for dynamic \$I_{BO}\$ and \$V_{BO}\$ parameters](#)
2. See [Figure 11: Test circuit 2 for \$I_{BO}\$ and \$V_{BO}\$ parameters](#)
3. See [Figure 12: Test circuit 3 for dynamic \$I_H\$ parameter](#)
4. $V_R = 50\text{ V}$ bias, $V_{RMS} = 1\text{ V}$, $F = 1\text{ MHz}$
5. $V_R = 2\text{ V}$ bias, $V_{RMS} = 1\text{ V}$, $F = 1\text{ MHz}$

Figure 2. Pulse waveform

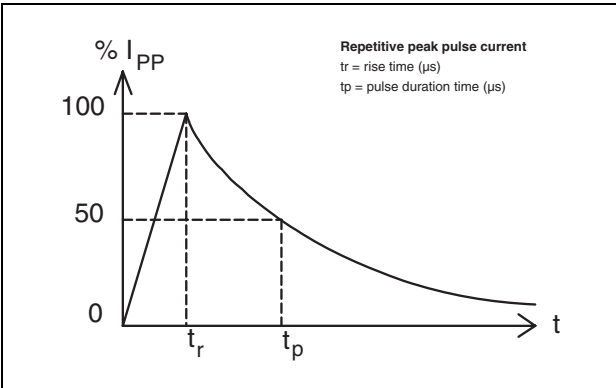


Figure 3. Non repetitive surge peak on-state current versus overload duration

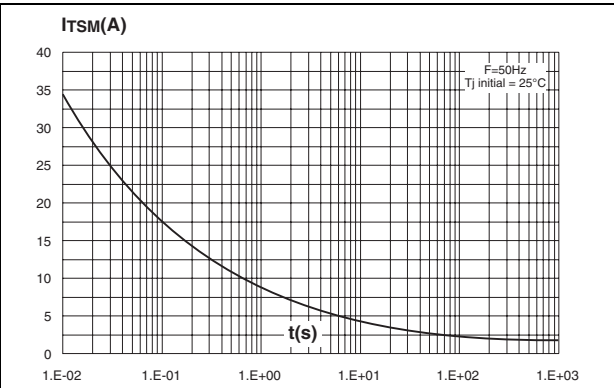


Figure 4. On-state voltage versus on-state current (typical values)

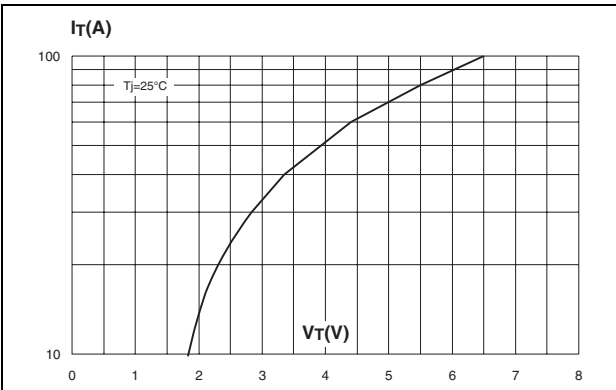


Figure 5. Relative variation of holding current versus junction temperature

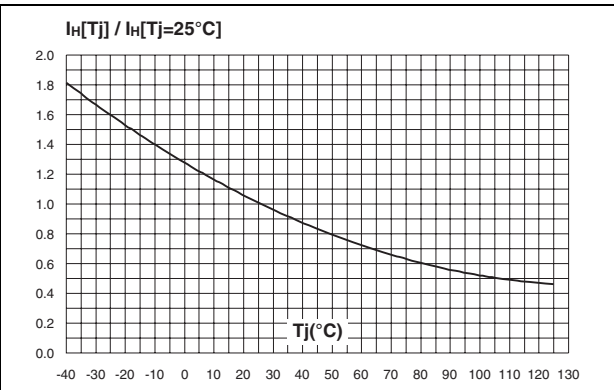


Figure 6. Relative variation of breakover voltage versus junction temperature

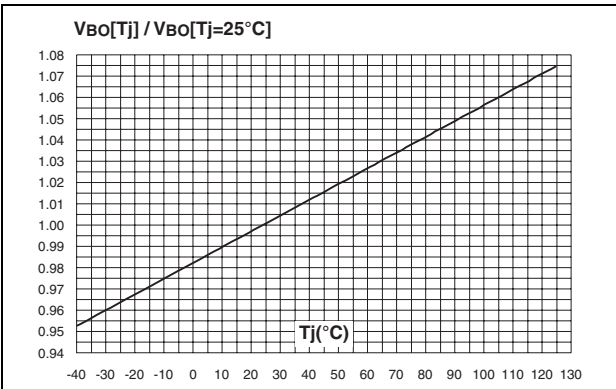


Figure 7. Relative variation of leakage current versus junction temperature (typical values)

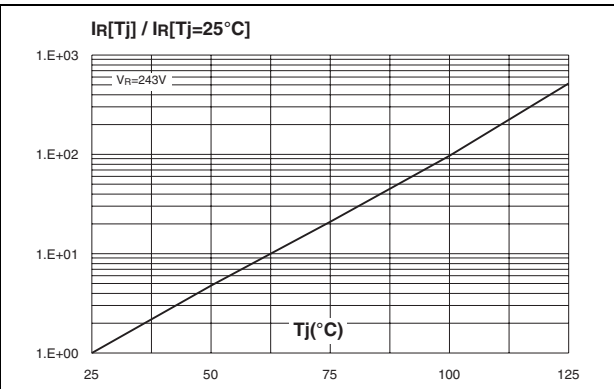


Figure 8. Variation of thermal impedance junction to ambient versus pulse duration

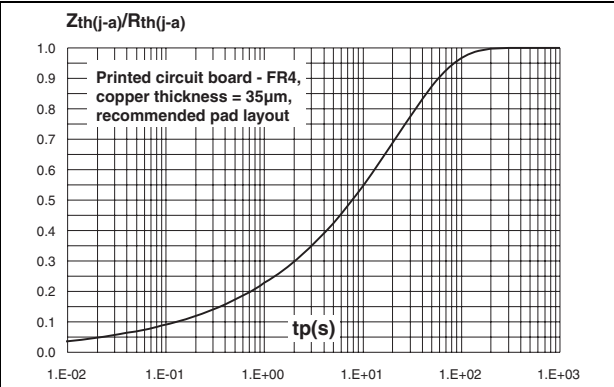


Figure 9. Relative variation of junction capacitance versus reverse voltage applied (typical values)

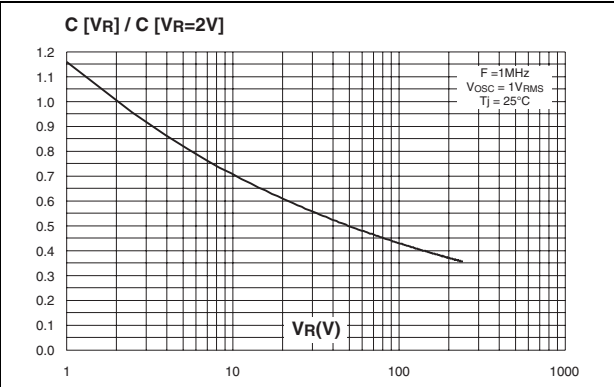


Figure 10. Test circuit 1 for dynamic I_{BO} and V_{BO} parameters

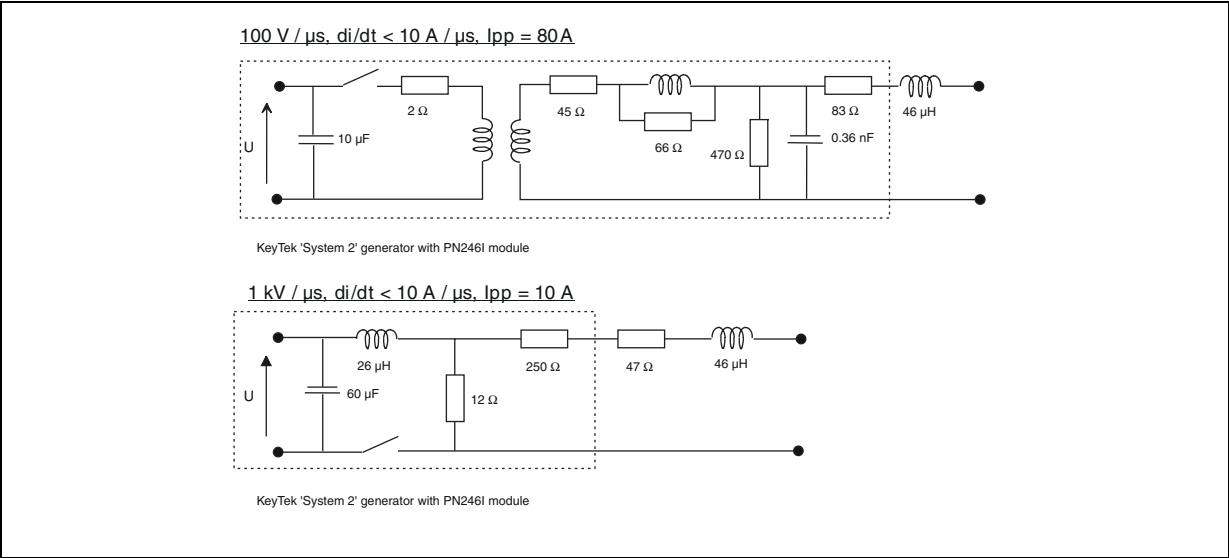
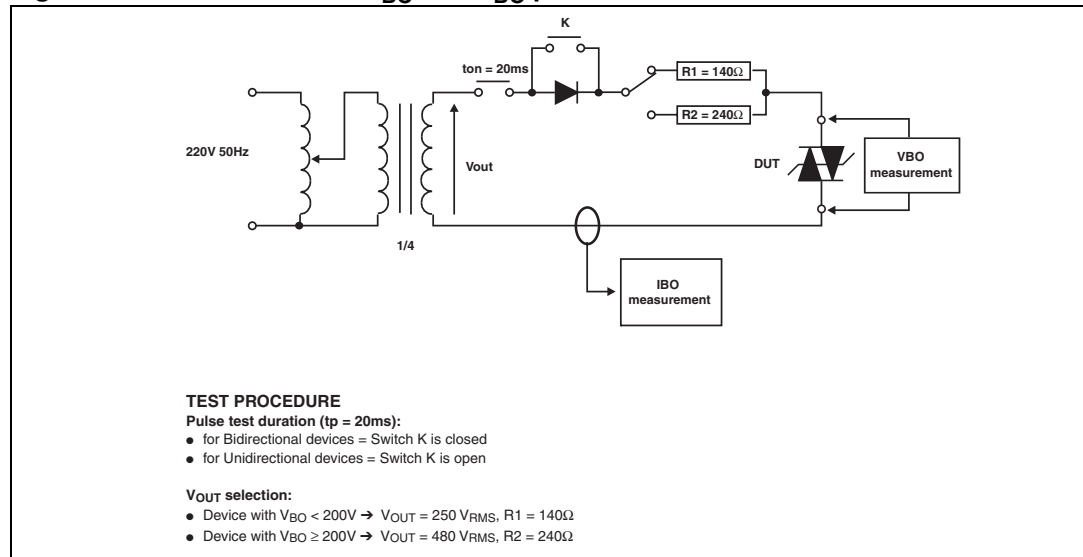
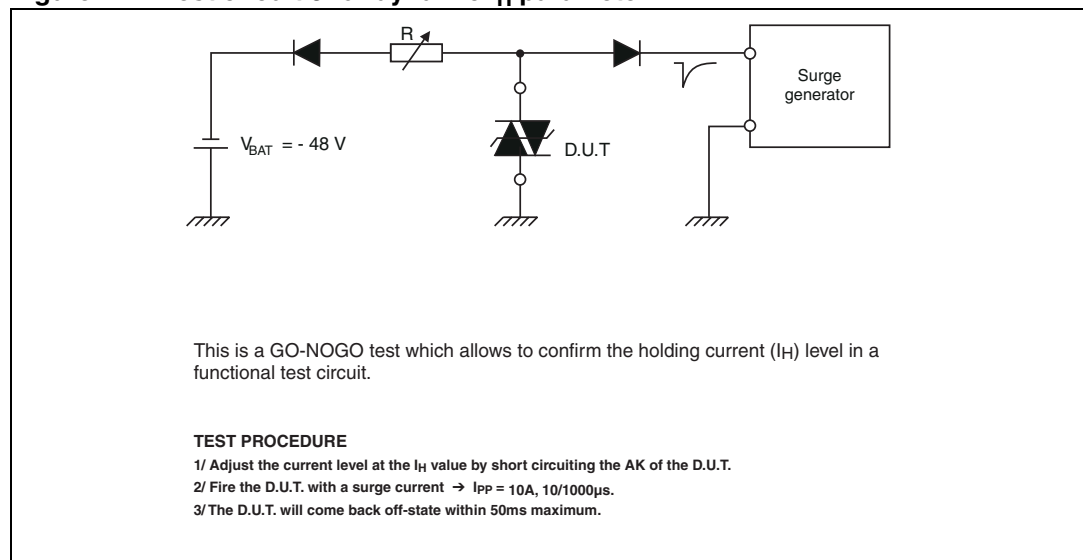
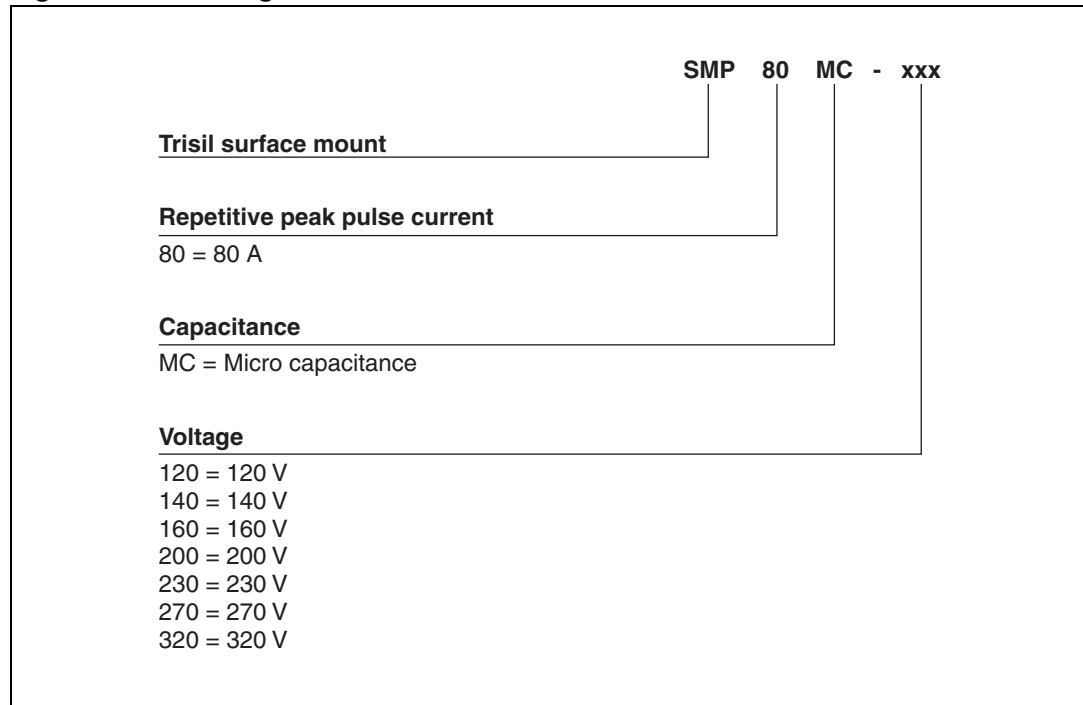


Figure 11. Test circuit 2 for I_{BO} and V_{BO} parametersFigure 12. Test circuit 3 for dynamic I_H parameter

2 Ordering Information Scheme

Figure 13. Ordering information scheme



3 Package information

- Epoxy meets UL94, V0
- Lead-free package

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK® is an ST trademark.

Table 5. SMB dimensions

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A1	1.90	2.45	0.075	0.096
A2	0.05	0.20	0.002	0.008
b	1.95	2.20	0.077	0.087
c	0.15	0.40	0.006	0.016
E	5.10	5.60	0.201	0.220
E1	4.05	4.60	0.159	0.181
D	3.30	3.95	0.130	0.156
L	0.75	1.50	0.030	0.059

Figure 14. Footprint dimensions in mm (inches)

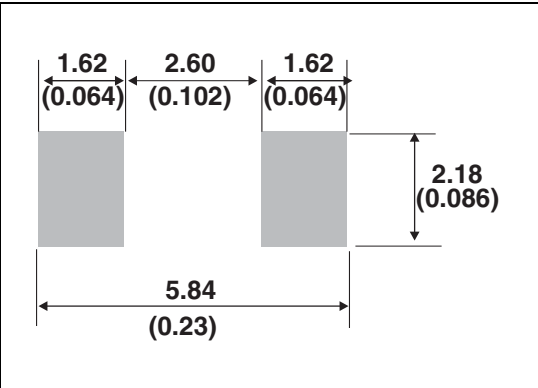
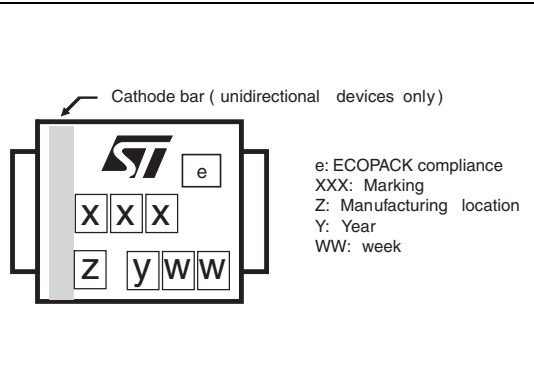


Figure 15. Marking layout⁽¹⁾



1. Marking layout can vary according to assembly location.

4 Ordering information

Table 6. Ordering information

Part Number	Marking	Package	Weight	Base qty	Delivery mode
SMP80MC-120	TP12	SMB	98 mg	2500	Tape and reel
SMP80MC-140	TP14				
SMP80MC-160	TP16				
SMP80MC-200	TP20				
SMP80MC-230	TP23				
SMP80MC-270	TP27				
SMP80MC-320	TP32				

5 Revision history

Table 7. Document revision history

Date	Revision	Changes
September-2001	1	First issue.
11-May-2005	2	New types introduction.
20-Jun-2005	3	Qualification of new types
18-Jan-2007	4	Added product SMP80MC-320
09-Feb-2012	5	Added UL statement in <i>Complies with the following standards</i>

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